

ABSTRACT

Disclosed is a method for forming a semiconductor assembly and the resulting assembly in which a flowable adhesive material which secures a die to a support and does not form an adhesive fillet. A flowable
5 adhesive is deposited between the die and support so that it covers about 50 to about 90 percent of the bottom surface area of the die after the die is mounted to the support. The reduced surface coverage area prevents formation of an adhesive fillet.